

SNAP High-Density Digital I/O Modules

Features

- 16 or 32 digital input points or output points in one compact SNAP module
- Up to 16 high-density digital modules on a SNAP rack, making up to 512 digital points available on one rack
- Convenient pluggable wiring harness, breakout racks, and header cables (available separately)
- Rugged packaging
- Operating temperature: 0 to 70 °C

Description

SNAP high-density digital (HDD) modules from Opto 22 provide 16 or 32 digital input or output points in one compact SNAP module. All HDD modules work with the SNAP PAC System, which consists of SNAP PAC controllers and brains, SNAP PAC racks, SNAP I/O modules, and PAC Project software.

SNAP high-density digital modules are ideal for OEMs and for anyone who has high point-count applications. The high-density point configuration reduces per-point costs of digital I/O systems by providing up to eight times as many I/O points in the same space.

The following high-density digital modules are available:

- The **SNAP-IDC-32** digital input module, with 32 input points, can be used to sense on/off status for 10–32 VDC inputs from sources such as proximity switches, limit switches, push buttons, and pilot switches.
- The **SNAP-IDC-16** digital input module offers 16 points with channel-to-channel isolation. It can sense on/off status for 10–32 VDC/VAC loads.
- **SNAP-IAC-16** and **SNAP-IAC-A-16** digital input modules each have 16 points with channel-to-channel isolation. These modules sense on/off status for 90–140 VAC (SNAP-IAC-16) or 180–280 VAC (SNAP-IAC-A-16).
- SNAP-ODC-32-SRC and SNAP-ODC-32-SNK digital output modules have 32 points and can switch on and off 5–60 VDC loads, either sourcing or sinking.

All HDD input modules feature automatic counting and latching. The DC models are ideal for detecting low-voltage auxiliary contacts.



SNAP-IDC-32 high-density digital input module

Part Numbers

| Part | Description |
|--------------------|--|
| Modules | |
| SNAP-IDC-32 | SNAP 32-point digital input module, 10–32 VDC |
| SNAP-IDC-16 | SNAP isolated 16-point digital input module, 10–32 VDC/VAC |
| SNAP-IAC-16 | SNAP isolated 16-point digital input module, 90–140 VAC/VDC |
| SNAP-IAC-A-16 | SNAP isolated 16-point digital input module, 180–280 VAC/VDC |
| SNAP-ODC-32-SRC | SNAP 32-point digital output module, 5–60 VDC load sourcing |
| SNAP-ODC-32-SNK | SNAP 32-point digital output module, 5–60 VDC load sinking |
| Accessories | |
| SNAP-HD-ACF6 | 6 ft. (1.8 m) wiring harness assembly for SNAP 16-point digital modules |
| SNAP-HD-CBF6 | 6 ft. (1.8 m) wiring harness for SNAP 32-point digital modules |
| SNAP-HD-BF6 | 6 ft. (1.8 m) header cable for SNAP 32-point digital modules and breakout racks |
| SNAP-IDC-HDB | Fused breakout rack for SNAP 32-point digital input modules |
| SNAP-ODC-HDB | Fused breakout rack for SNAP 32-point output modules |
| SNAP-HD-G4F6 | 6 ft. (1.8 m) header cable for SNAP-ODC-32-SNK digital modules and G4PB16 mounting racks |
| OPTOTERMINAL-G20 | Terminal with operator controls for use with SNAP high-density digital modules |

SNAP High-Density Digital I/O Modules

Comparing SNAP High-Density and 4-Channel Digital Modules

| Item | SNAP High-Density Digital Modules | 4-Channel SNAP Digital Modules |
|--|---|--|
| Number of points on module | 16 or 32, depending on module | 4 |
| Isolation and fusing | 16-point input modules: Each point is optically isolated from other points on the module. 32-point input and output modules: The module is divided into four groups of eight points. Groups are isolated from each other, but points within a group are not isolated from each other. Groups must be externally fused. | Input modules: Each point is optically isolated from other points on the module. Most output modules: Points are not isolated from each other. Points share a common fuse. For isolated modules, see the <i>SNAP Digital Output Modules Data Sheet</i> (form #1144). |
| Status LEDs | None; use the handheld OptoTerminal-G20 for module diagnostics and commissioning, or for 32-point modules, connect to an optional breakout rack. | One for each point, located on top of module. |
| Polling time from I/O processor to module ¹ | 2–30 ms typical ² | 0.5–2 ms typical ² |
| Module turn-on/off time ¹ | 16-point input modules: 15–20 ms 32-point input modules: 6 ms Output modules: 100 microseconds | Varies by module. Examples: <ul style="list-style-type: none"> • SNAP-IDC5-FAST: 25 microseconds • SNAP-IDC5: 5 ms turn-on, 15 ms turn-off |
| On/off status | Yes | Yes |
| Input latching | Yes | Yes |
| Counting on digital input modules | Counting occurs on the module. ³ Counting is available with any compatible I/O processor (including SNAP-PAC-R2 and SNAP-PAC-EB2). Counting speeds: On 32-point modules, 0–50 Hz @ 50% duty cycle On 16-point modules, 0–25 Hz @ 50% duty cycle | High-speed counting occurs on the I/O processor (brain or on-the-rack controller) and can be configured for any point. (High-speed counting is available on SNAP-PAC-R1 and SNAP-PAC-EB1 processors.) Counting speed varies based on the processor and the speed of the module. Example: SNAP-PAC-EB1 brain with SNAP-IDC5-FAST: up to 20 KHz |
| Watchdog timer | Firmware 8.1 and higher, yes. Firmware 8.0 and lower, no. | Yes |
| On-pulse and off-pulse measurement | Firmware 8.1 and higher, yes. Firmware 8.0 and lower, no. | Yes |
| Pulse generation | Yes | Yes |
| Digital events | Firmware 8.1 and higher, yes. Firmware 8.0 and lower, no. | Yes |

1 Actual turn-on and turn-off times equal the polling time plus the module time.

2 Polling time varies based on the SNAP I/O processor (brain or on-the-rack controller), processor configuration, and Ethernet host communication activity.

3 The high-density digital module uses a 16-bit counter, but the processor used with the module accumulates counts to 32 bits by periodically getting and clearing the module's counts and adding to current values. Update time varies based on number of modules and Ethernet communication demands.

SNAP High-Density Digital I/O Modules

Specifications (continued)

| | SNAP-ODC-32-SRC | SNAP-ODC-32-SNK |
|--|--|--|
| Switching Voltage | 5–60 VDC | 5–60 VDC |
| Nominal Switching Voltage | 12–24 VDC | 12–24 VDC |
| Logic Voltage and Current | 5 VDC \pm 0.1 @ 150 mA | 5 VDC \pm 0.1 @ 150 mA |
| Output Arrangement | 32 output channels; 4 groups of 8 outputs each. Points in each group share a common positive connection. | 32 output channels; 4 groups of 8 outputs each. Points in each group share a common negative connection. |
| Maximum Number of HDD Modules on One Mounting Rack | 16 | 16 |
| Indicators | None; use optional OptoTerminal-G20 diagnostic display or breakout rack. | None; use optional OptoTerminal-G20 diagnostic display or breakout rack. |
| Polling time from I/O processor to module ¹ | 2–30 ms typical ² | 2–30 ms typical ² |
| Output Turn-On/Off Time | 100 microseconds | 100 microseconds |
| Maximum Load per Point | 0.25 A | 0.25 A |
| Forward Drop | 0.15 VDC @ 0.25 A | 0.15 VDC @ 0.25 A |
| Maximum Off State Voltage | 60 VDC | 60 VDC |
| Reverse Voltage | 0.6 VDC | 0.6 VDC |
| Surge (1 sec.) | 1 A | 1 A |

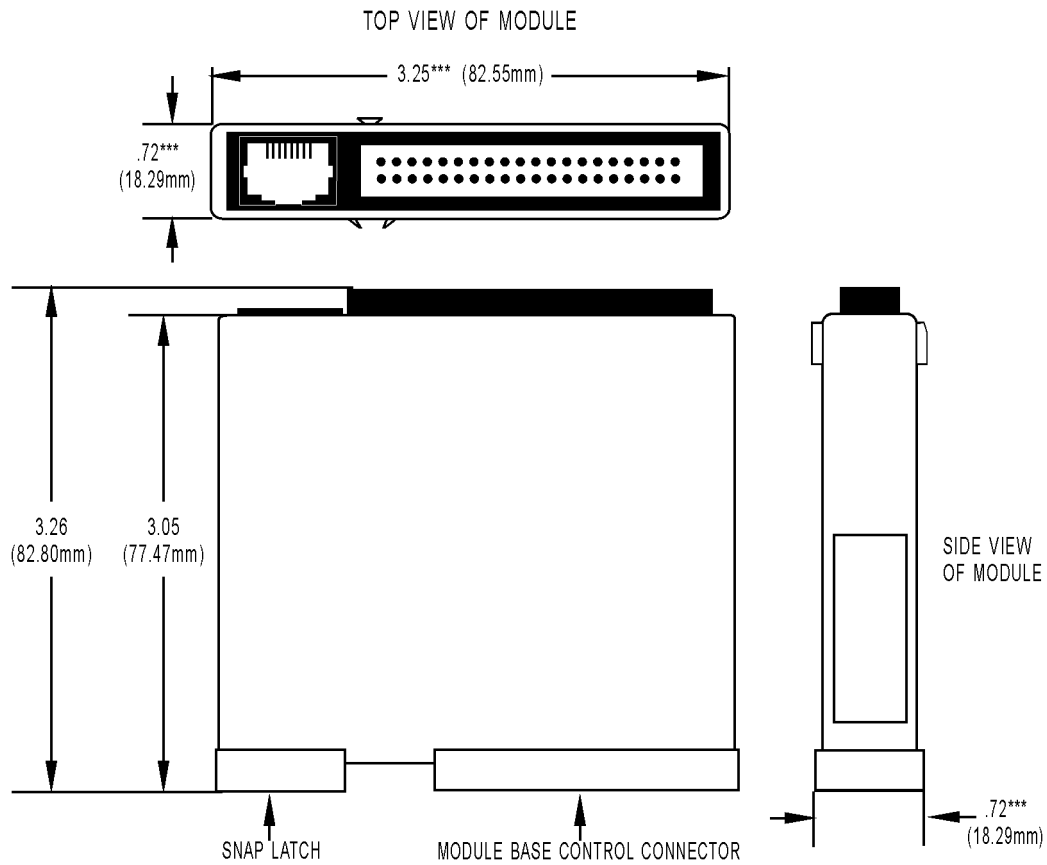
1 Affects turn-on and turn-off determination

2 Time varies based on the SNAP PAC I/O processor (brain or on-the-rack controller), processor configuration, and Ethernet host communication activity.

SNAP High-Density Digital I/O Modules

Dimensional Drawings

SNAP 32-Point Digital Modules



TOLERANCES LEGEND

* +/- .010" ** +/- .020"
*** +/- .030" **** +/- .060"
NO * REFERENCE ONLY

SNAP High-Density Digital I/O Modules

Dimensional Drawings (continued)

SNAP High-Density Digital Modules

